

Amendments to the Specification:

Please replace paragraph [0017] with the following amended paragraph:

[0017] It should be noted that if some residue of the adhesive material 24 remains on the surface of the conductive layers 14 or 16 after filling the holes and after it is B-staged, it can be easily removed by chemical or mechanical polishing processes 22 as are well known in the art. It should be noted that, at this point in the processing, no masks have been required for filling the holes so there are no registrations required, and any film material that may accidentally remain on the surface of the metal can be easily removed by polishing or other operations.